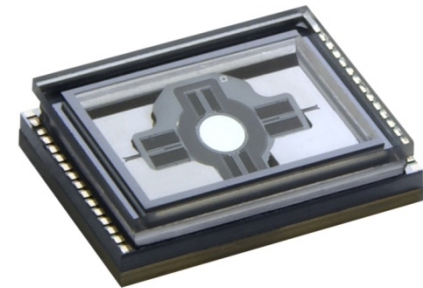

Hermetically Sealed 2D-MEMS Scanning Mirrors for High Resolution Imaging Applications

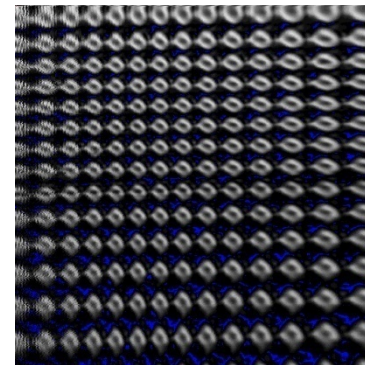
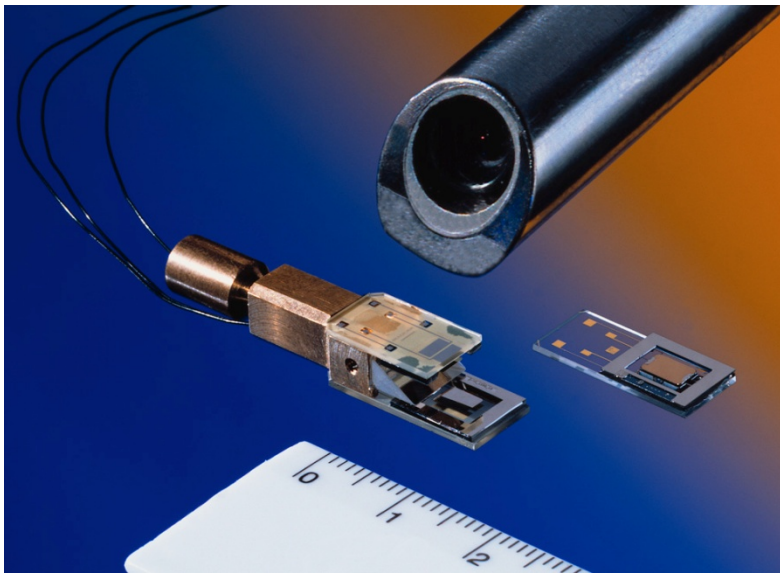
Ulrich Hofmann, Joachim Janes, Lars Ratzmann, Oliver Schwarzelbach
Fraunhofer Institute for Silicon-Technology ISIT

Ulrich Hofmann, Fraunhofer ISIT, Fraunhofer Strasse 1, D-25524 Itzehoe, Germany,
email: ulrich.hofmann@isit.fraunhofer.de,
Tel.: +49 4821 174553



MEMS-scanning mirrors developed at ISIT since 1995

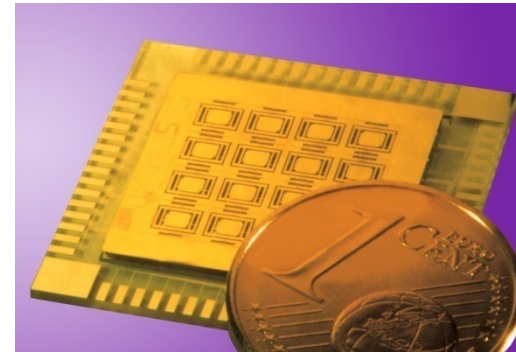
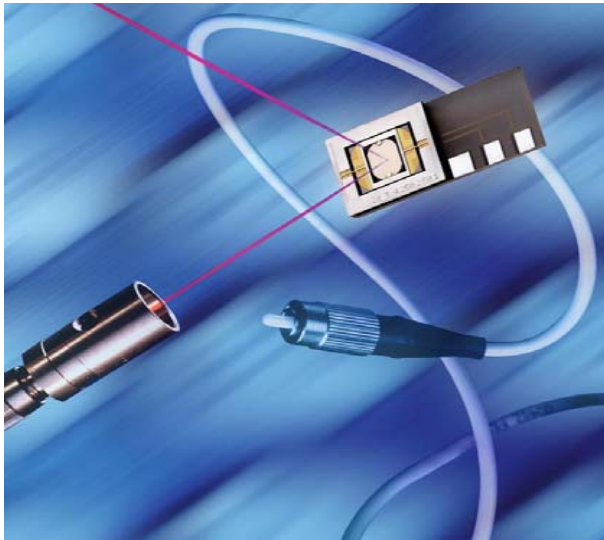
Miniature confocal laser scanning microscope for endoscopic *in situ* tumor diagnostics



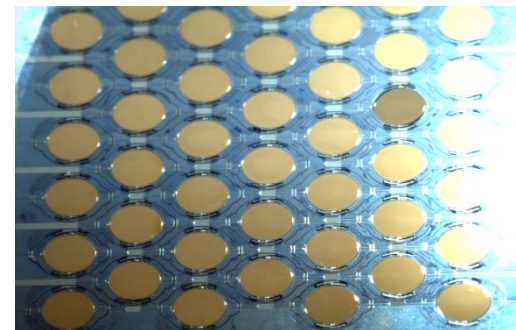
1024 x 1024 pixels
resolution: 2 μ m

MEMS scanning mirrors developed for telecommunication industry (1999..2003)

Optical cross connects

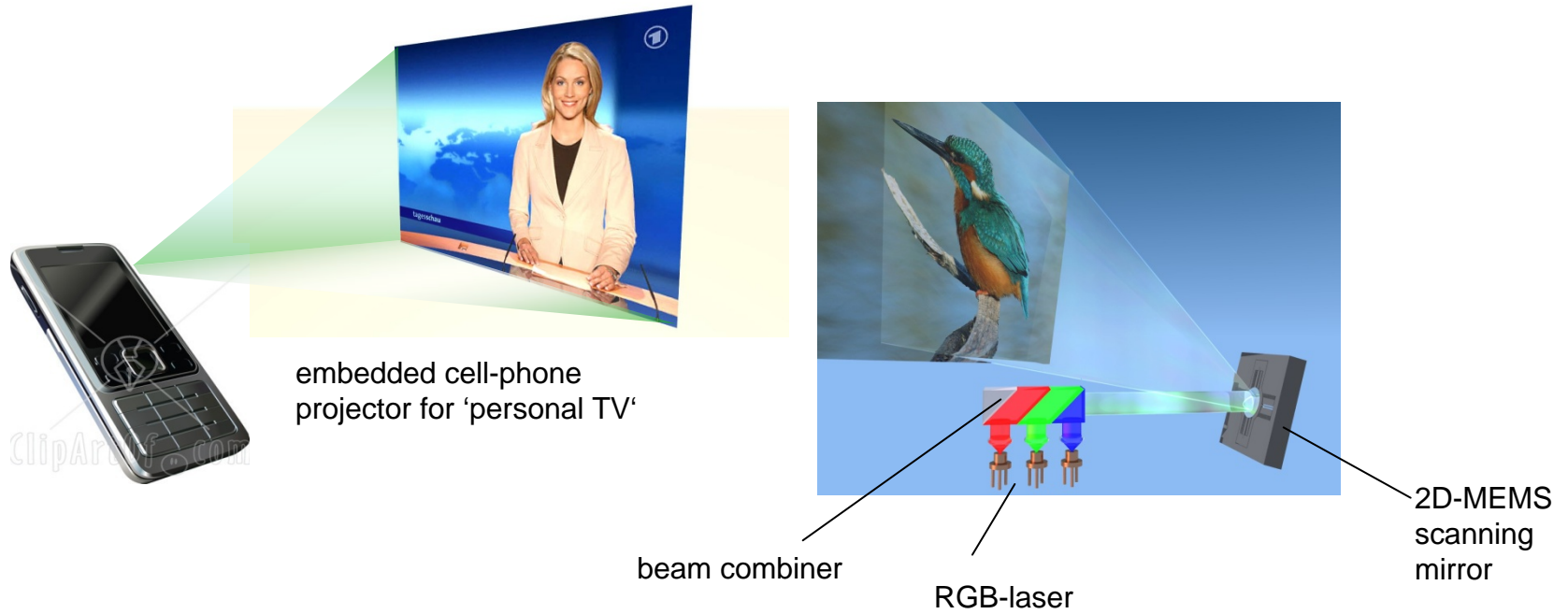


4 x 4
2D-scanner
array



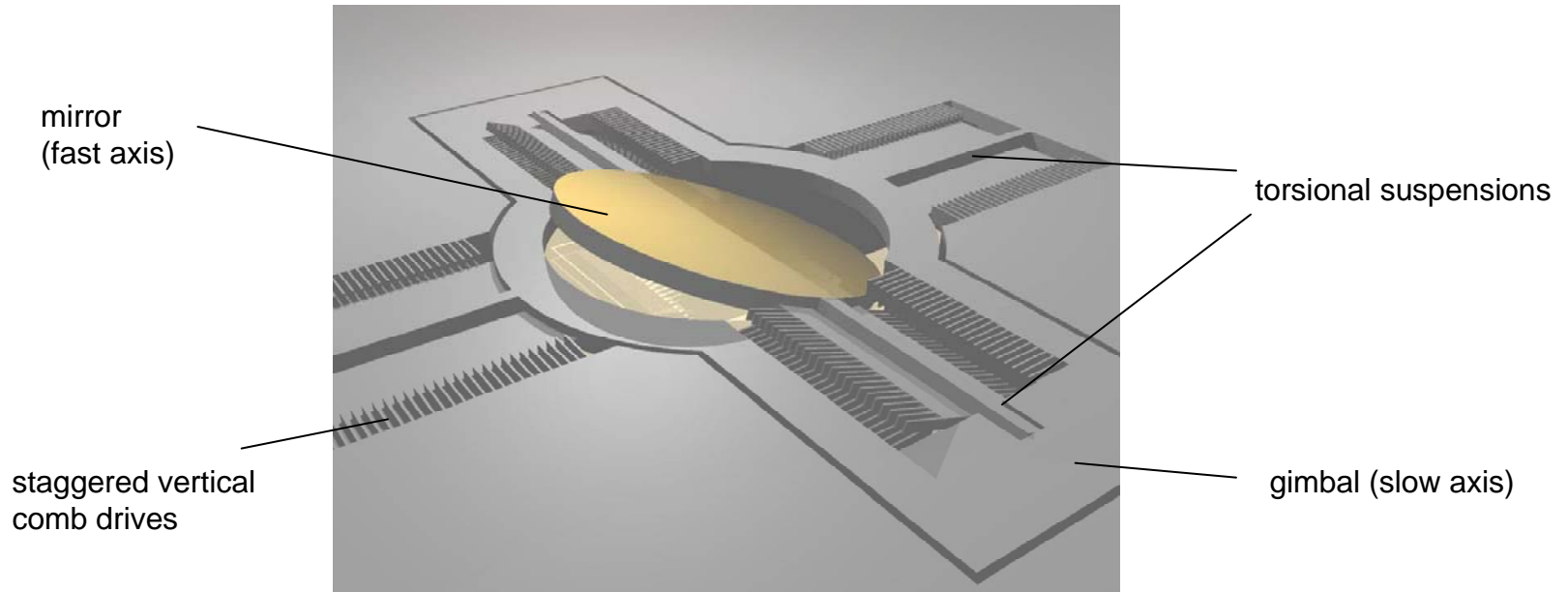
6 x 7
2D-scanner
array

high speed MEMS scanning mirrors for laser video projection displays

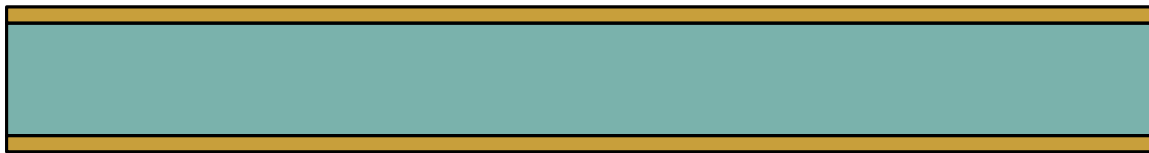


HDTV resolution (720 x 1280) requires a line projection frequency of 43,200 lines / sec !

electrostatic actuation of resonant 2D-MEMS-scanning mirrors



MEMS mirror fabrication



silicon oxide

silicon substrate

MEMS mirror fabrication



polysilicon 30µm

silicon oxide 1µm

silicon substrate 500µm

MEMS mirror fabrication



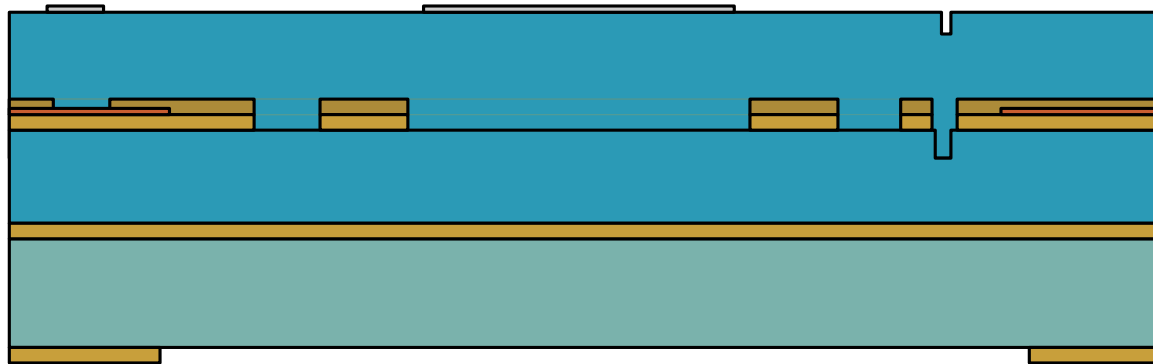
buried oxide mask +
embedded poly interconnects

polysilicon 30 μ m

silicon oxide 1 μ m

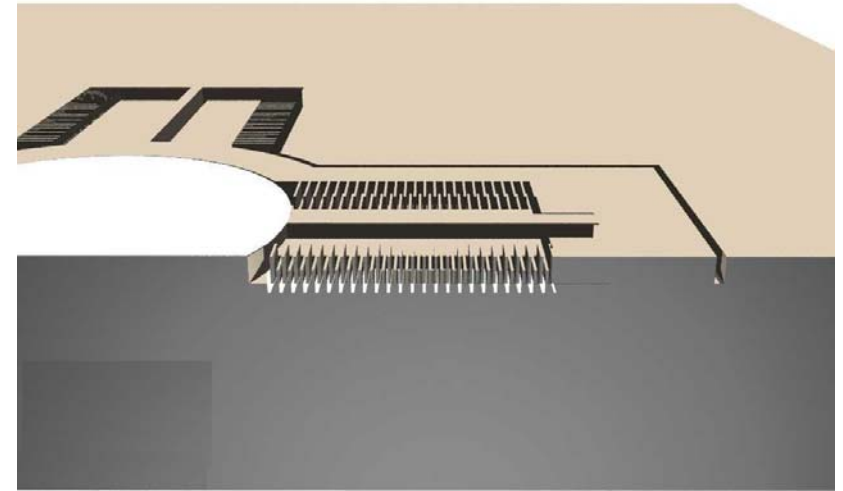
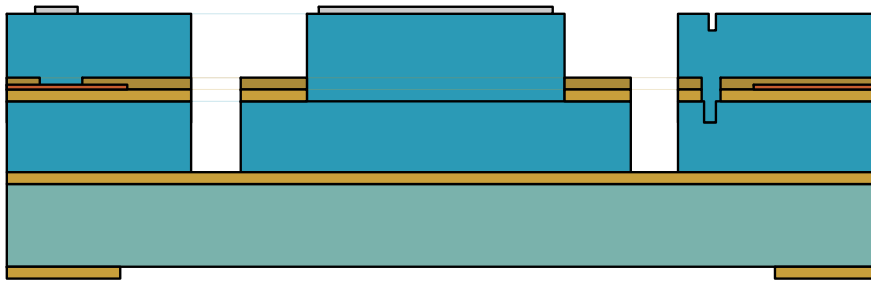
silicon substrate 500 μ m

MEMS mirror fabrication

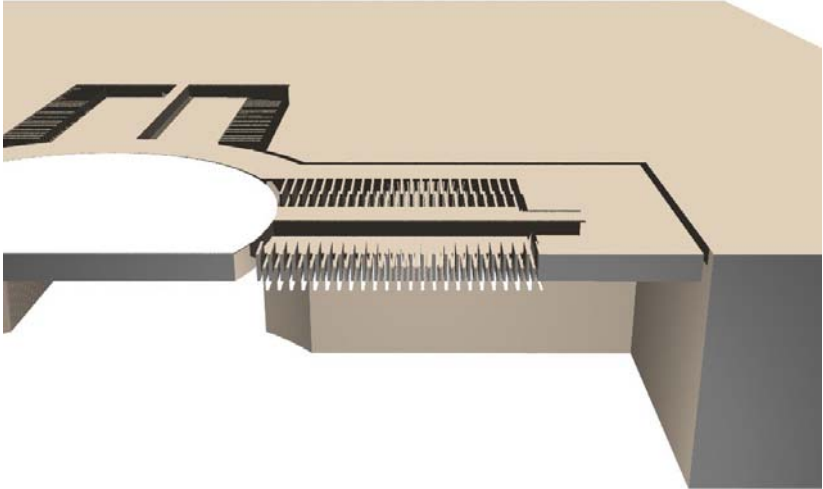
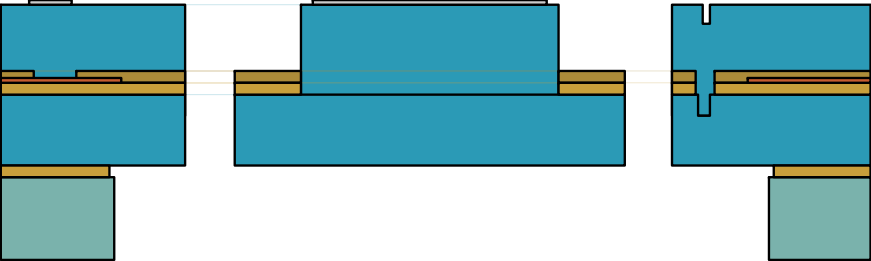


- aluminum 400nm
- polysilicon 30µm
- buried oxide mask +
embedded poly interconnects
- polysilicon 30µm
- silicon oxide 1µm
- silicon substrate 500µm

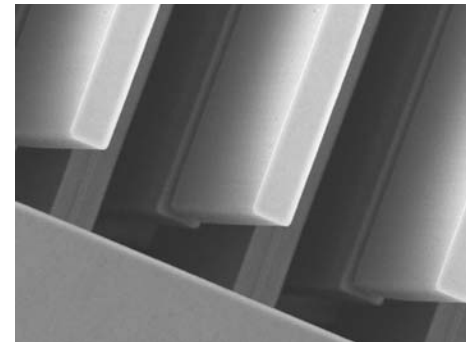
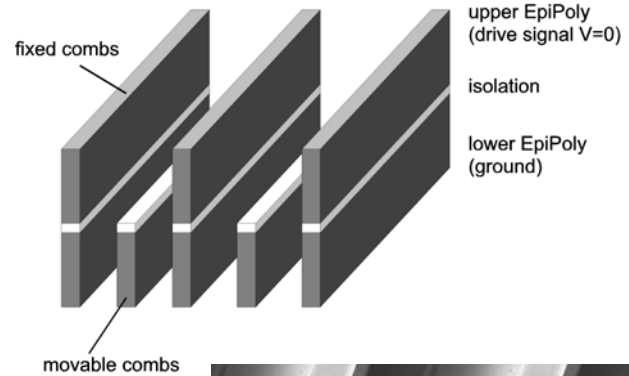
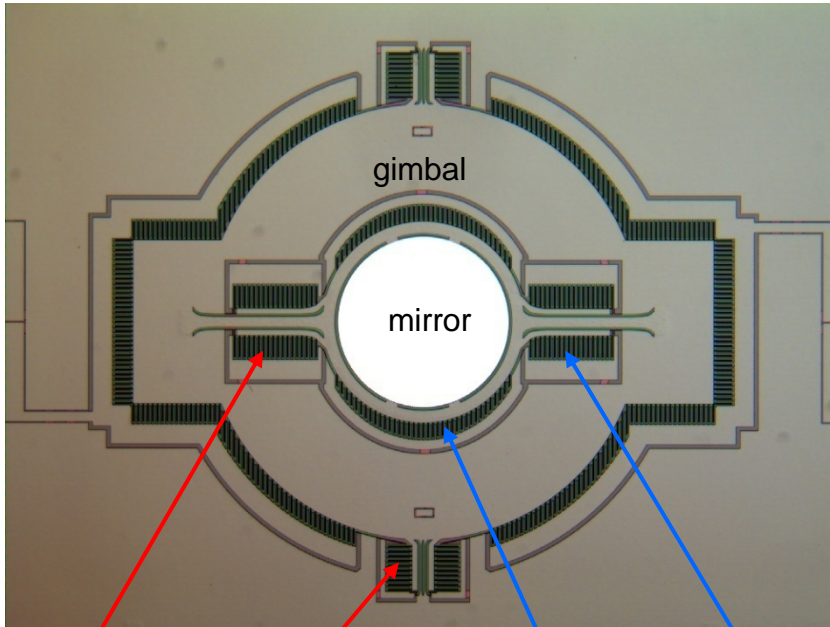
frontside patterning by deep reactive ion etching (DRIE)



backside-patterning by deep reactive ion etching (DRIE)



two-axis MEMS scanning mirror for laser projection



sensor electrodes fast axis

sensor electrodes slow axis

driving electrodes slow axis

driving electrodes fast axis

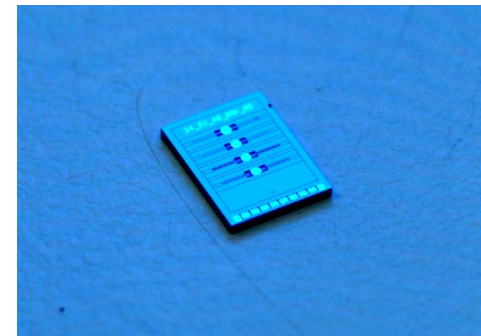
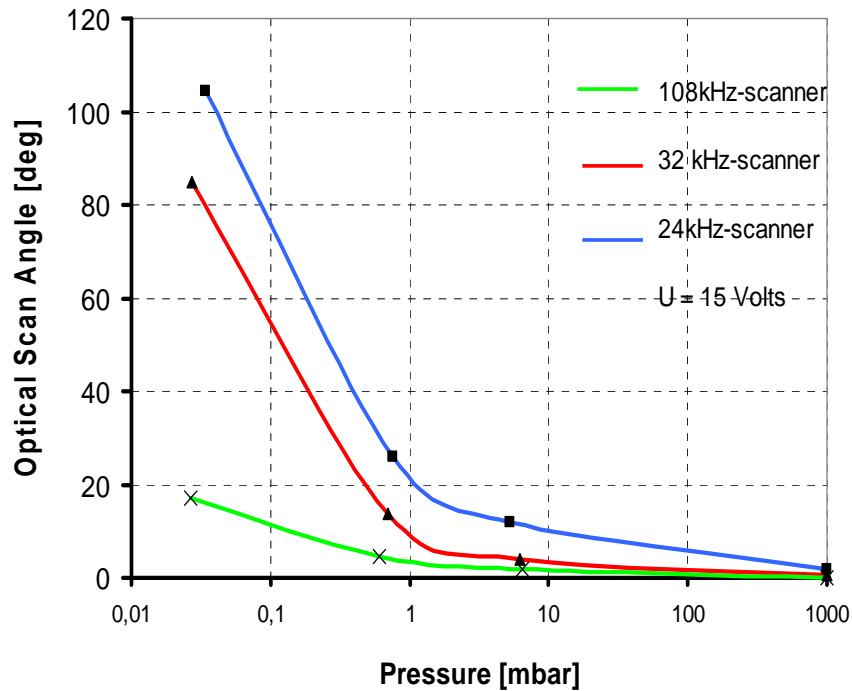
Fraunhofer ISIT 09

test of MEMS scanners in a vacuum chamber

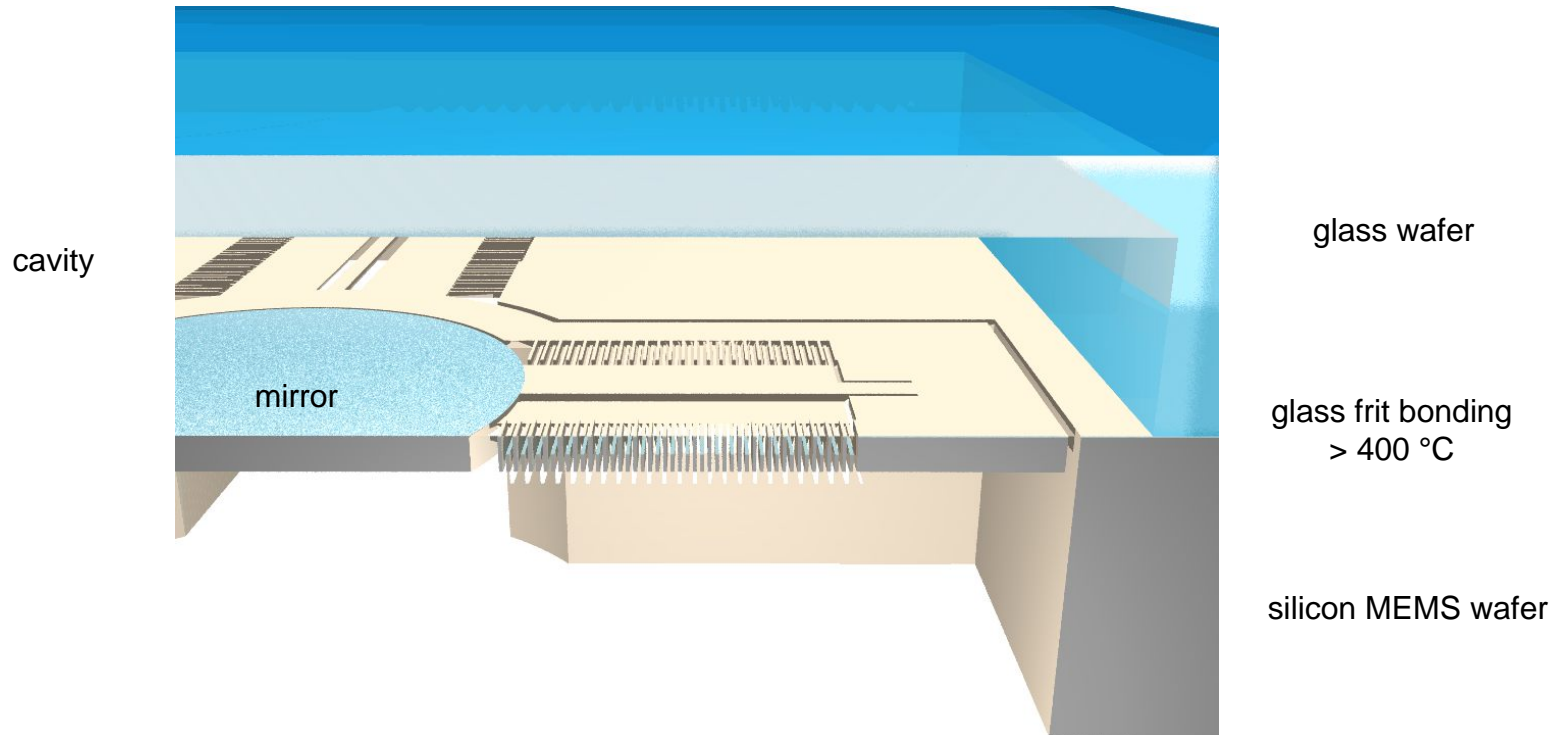


Fraunhofer ISIT 09

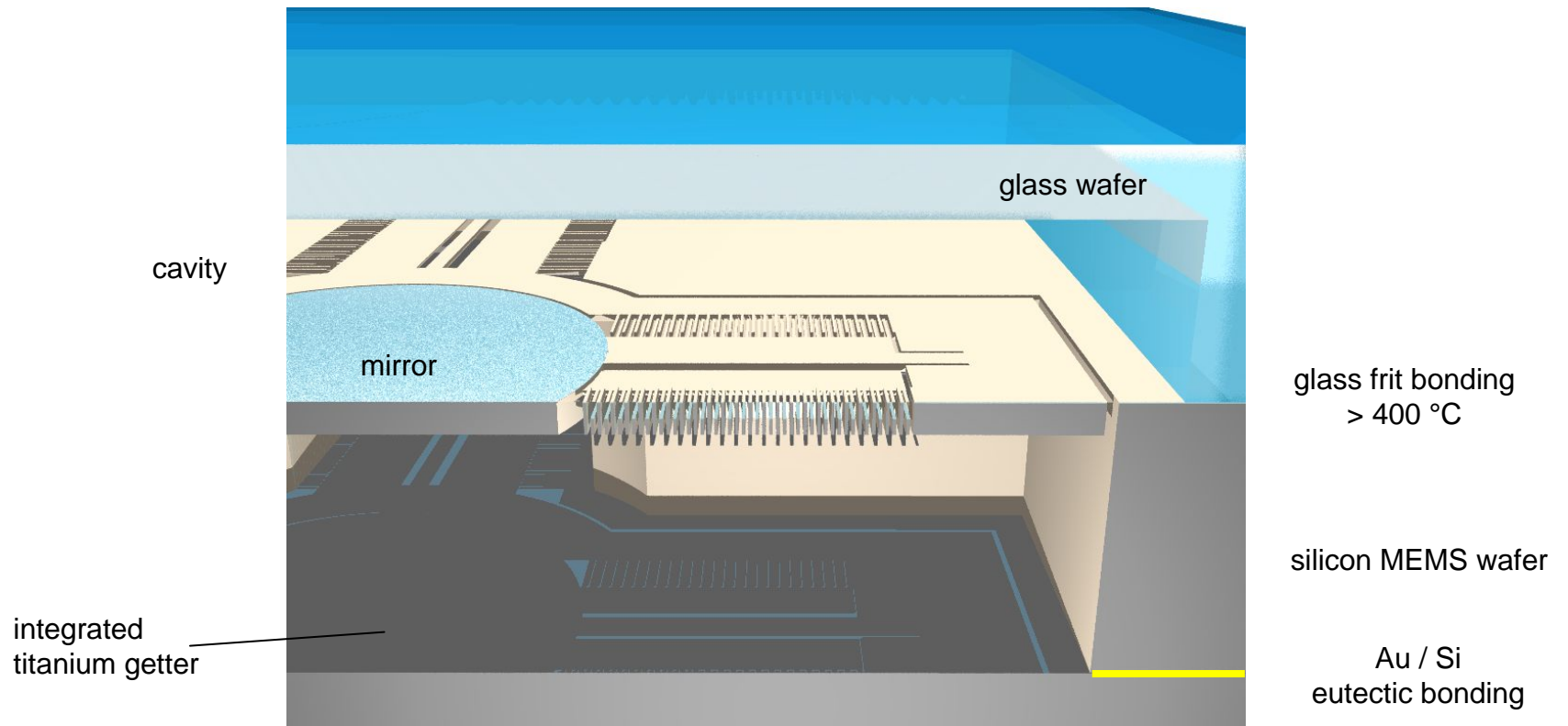
significant effect of air pressure on the resonance amplitude



vacuum encapsulation on wafer-level



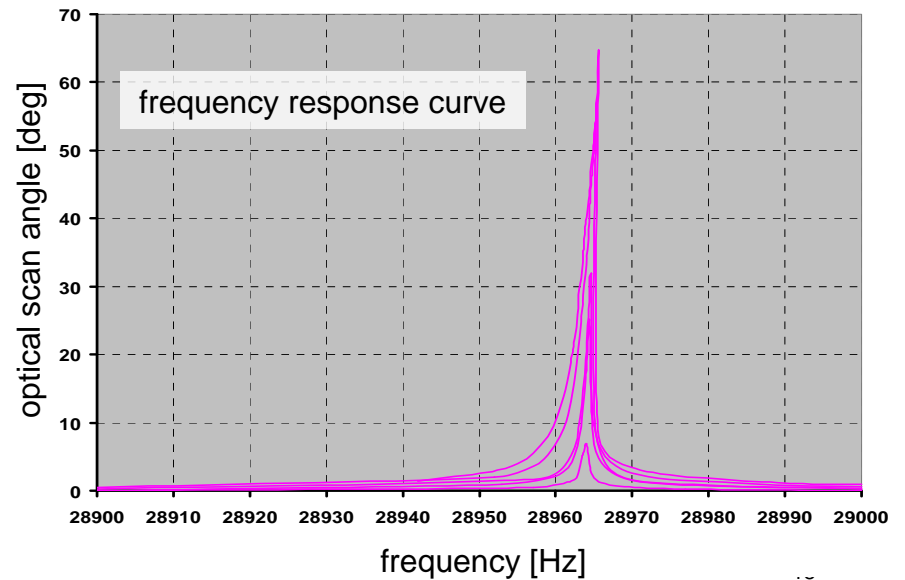
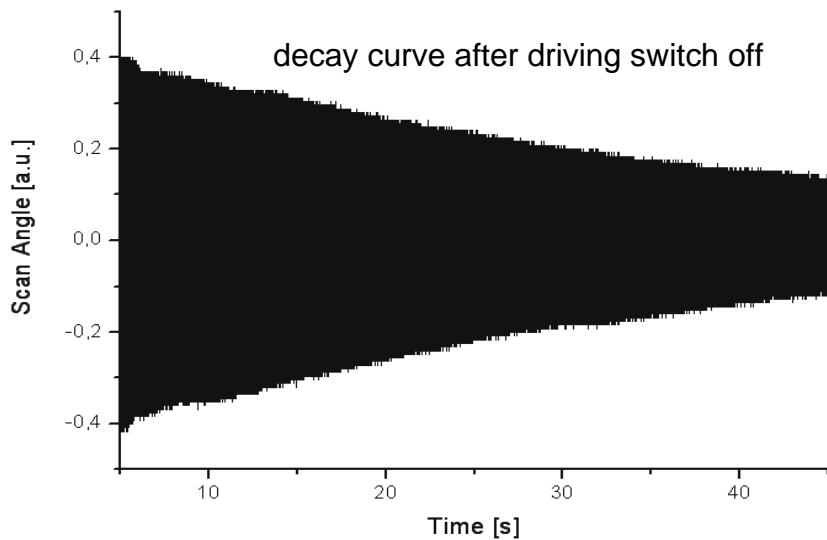
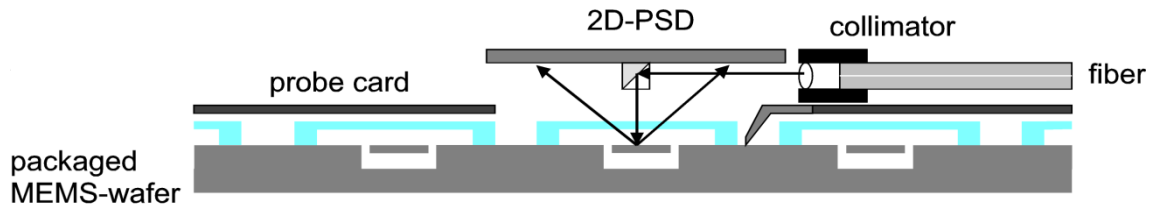
vacuum encapsulation on wafer-level



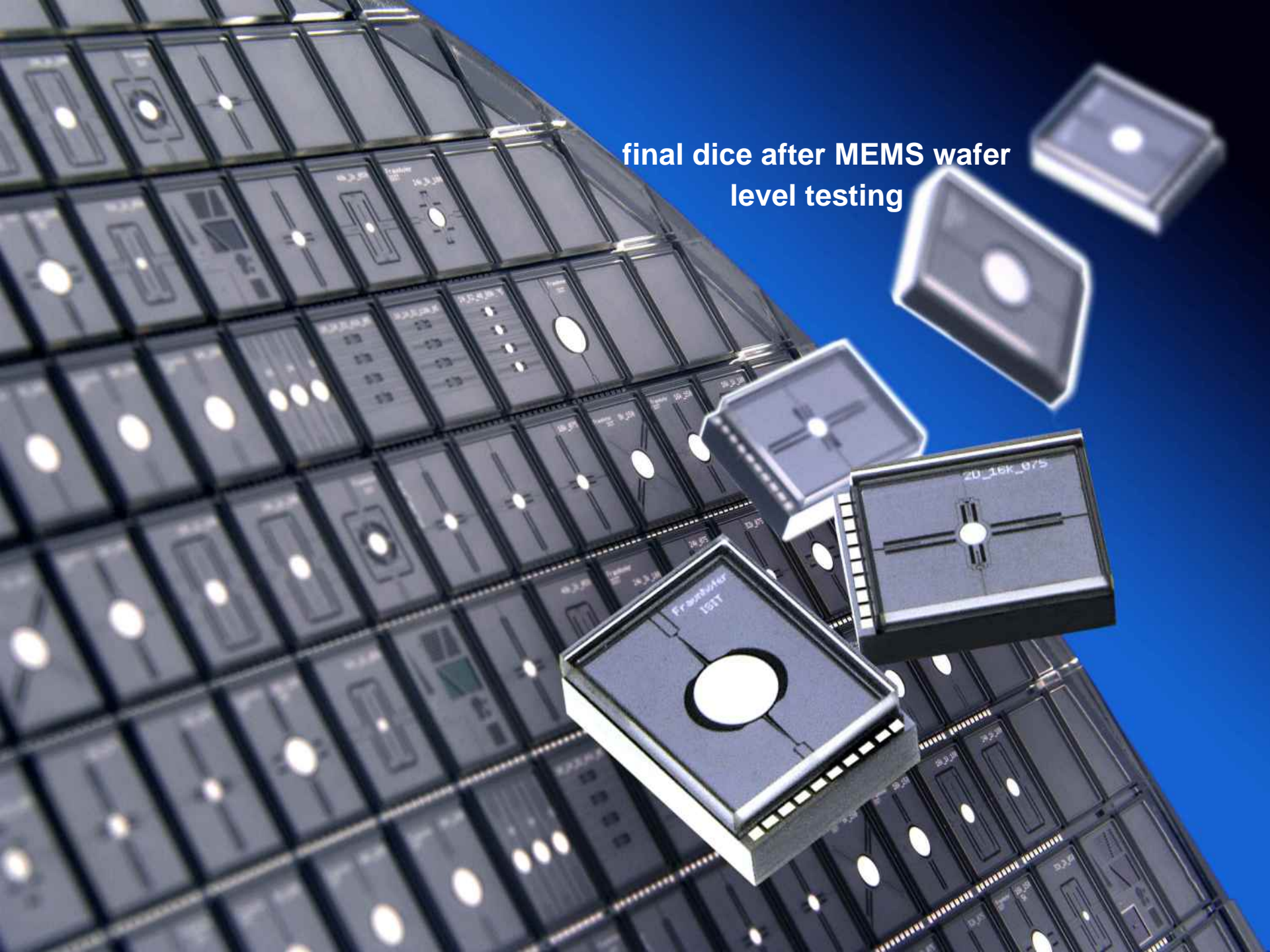


**MEMS scanning mirrors
vacuum packaged on wafer level**

opto-electromechanical characterization on wafer-level

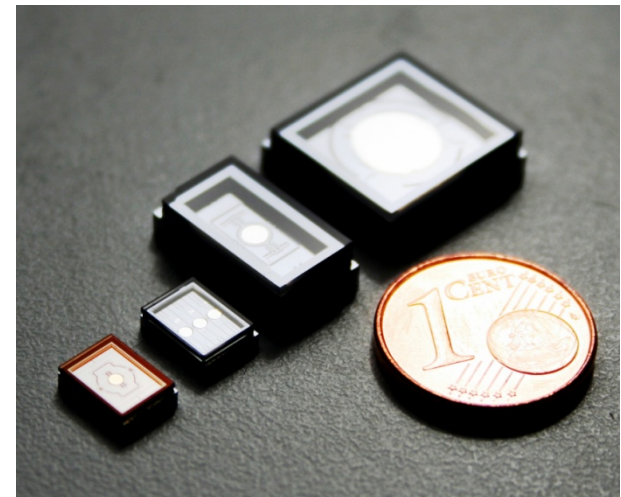


**final dice after MEMS wafer
level testing**

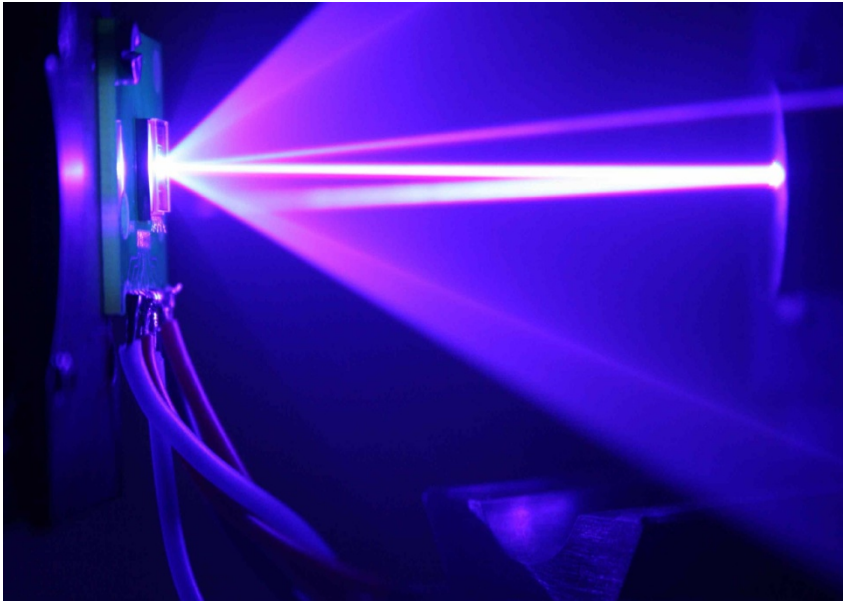


parameter-range of fabricated MEMS scanning mirrors

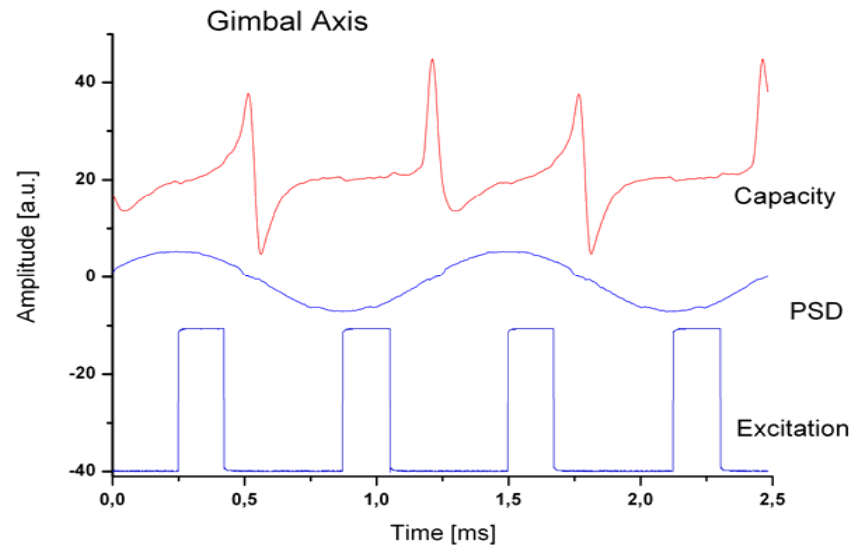
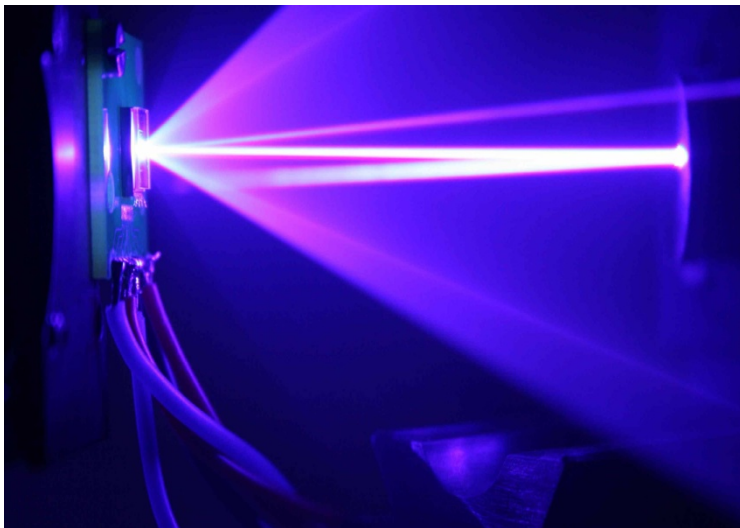
mirror aperture size:	0.5 mm .. 7 mm
scan frequencies fast axis:	16 kHz .. 108 kHz
scan frequencies slow axis:	150 Hz .. 2 kHz
total optical scan angle:	20° .. 120°
Q-factor:	> 60,000
power consumption:	0.1 μ W .. 1 mW
driving voltage:	5 .. 70 V



phase controlled Lissajous-scanning

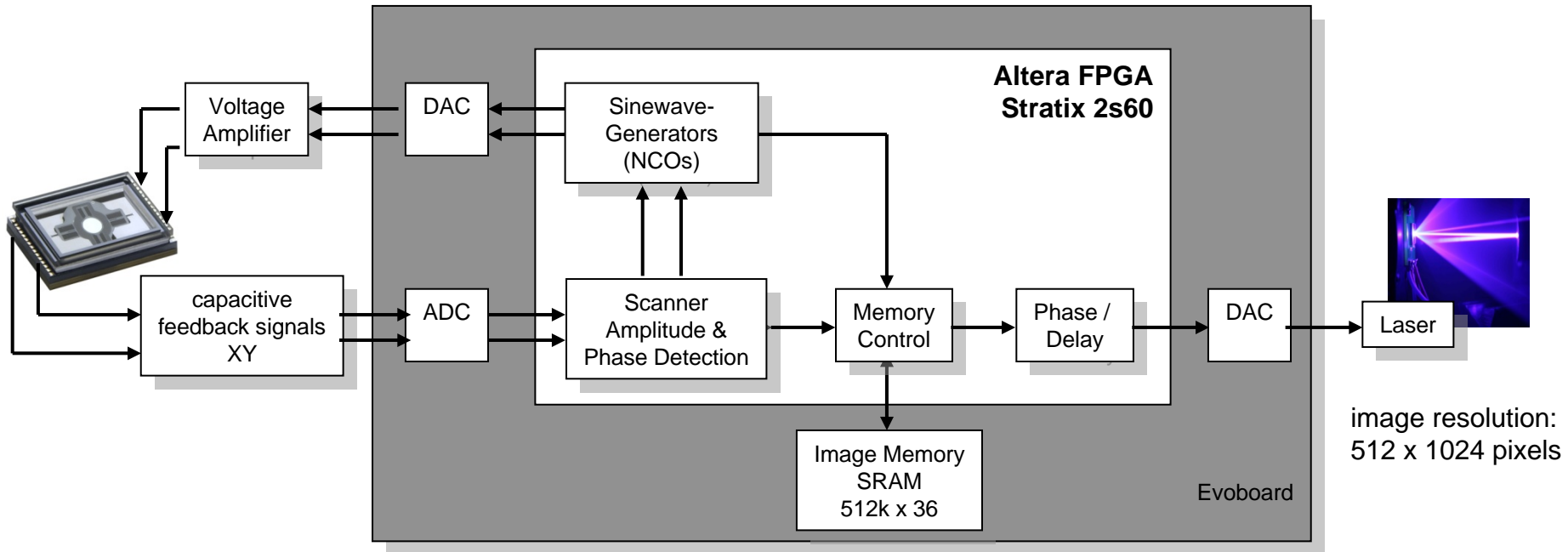


phase controlled Lissajous-scanning



- capacitive feedback enables stable phase controlled mirror operation
- enables synchronization of MEMS mirror and laser output for display and LIDAR applications
- enables also synchronization of MEMS mirror and detector signals in all imaging applications

synchronisation of MEMS mirror and laser in a Lissajous-projector



Lissajous laser projection

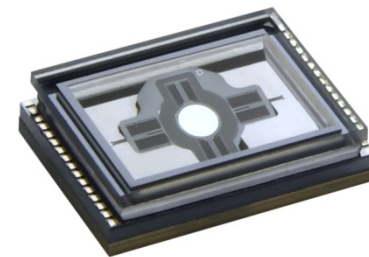


Lissajous laser projection



Summary

- hermetic wafer level packaging of MEMS scanning mirrors provides reliable protection against contamination by particles fluids or gases
- because of neglectable gas damping vacuum packaged MEMS scanning mirrors achieve outstanding dynamics i.e. scan angles up to 120 degree and scan speed up to 200,000 lines/sec
- vacuum encapsulation enables to drive very large mirrors with apertures up to 10 mm
- besides display applications the developed synchronization electronics can be used in high resolution real time imaging applications and LIDAR sensors.



**Thank you
for your attention !**

